

ABSTRACT OF Korean Patent Application No. 1994-024348

The present invention relates to a semiconductor fabricating apparatus having a shower-head. The shower-head deposits a film using plasma and thermal energy.

- 5 According to the present invention, in order to easily remove unnecessary gases deposited in the shower-head, a cooling function capable of controlling a temperature of the shower-head low is added to the semiconductor fabricating apparatus.

Moreover, in accordance with the present invention, an additional cooling device is attached to a conventional shower-head in forming an inter metal dielectric (IMD) as well
10 as forming a film by injecting gases in the course of fabricating an ultra large scale integration semiconductor. As a result, it is possible to suppress the film deposited on a shower-head surface maximally, to reduce a particle, to prolong the life of the shower-head depending on the formation of the film and to throughput hours in fabricating a semiconductor. Resultantly, operation hours of an apparatus can be increased.